



ASQED'09
1st Asia Symposium on
QUALITY ELECTRONIC DESIGN
July 15-16, 2009. KL, Malaysia

Event Overview



Benefits to Malaysia

- Gathering of global top expertise in Semiconductor and IC design, Nano/BioTech in Malaysia
- Create a platform for local universities and industry to share their views and explore new techniques of achieving quality products through a bevy of activities
- Encourage local technical expertise to publish their innovations and R&D work
- Encourage graduates to join Semiconductor Industry
- Encourage undergraduate studies in Engineering Schools
- To create awareness and promotion of Malaysia as a Science and Technology hub and International Technology events location.

Conference at a glance

Date	Time			
Wednesday 7/15/2009	8:30am-8:45am	Opening Ceremony		
		Keynote Speeches KN#1 8:45am-9:30am KN#2 9:30am-10:15am Break 10:15am-10:45am KN#3 10:45am-11:30am KN #4 11:30-12:15pm		
	12:00noon-1:30pm	ISQED-Asia Luncheon Awards Luncheon Speech		
	1:30pm-3:00pm	Session 1A (4)	Session 1B (4)	Session 1C (4)
	3:00pm-3:30pm	Afternoon Break		
	3:30pm-5:30pm	Session 2A (5)	Session 2B (5)	Session 2C (5)
Thursday 7/16/2009	8:30am-10:00am	Session 3A (4)	Session 3B (4)	Tutorial Track
	10:00am-10:30am	Morning Break		
	10:30am-12:00noon	Session 4A (4)	Session 4B (4)	Tutorial Track
	12:00noon-1:00pm	Lunch Break		
	1:00pm-3:00pm	Session 5A (5)	Session 5B (5)	Tutorial Track
	3:00pm-3:30pm	Afternoon Break		
	3:30pm-5:30pm	Session 6A (5)	Session 6B (5)	Tutorial Track

Program Notes:

- 5 keynote speeches; 4 in the morning and one during lunch. These keynotes will cover: Solar Energy, Biotechnology, Nanotechnology, Semiconductor/Packaging, and EDA.
- 14 technical sessions consisting of near 63 papers (more can be accommodated if necessary)
- One tutorial track consisting of 4 topics/speakers

Organizing Committee Overview



Conference Committee Members

Conference Chair	JA Lew	Vice Chairman MIMs
Publicity Chair	1. Dr. A A Iranmanesh	ISQED, P.O.Box 2336, Sunnyvale, CA 94087-0336, USA
	2. Dato' Jalilah Baba	Malaysian Industrial Development Authority, 2nd Floor, Block 4, Plaza Sentral, Jalan Stesen Sentral 5, 50470 Kuala Lumpur (MIDA)
Grants Chair	Dr. Norlela Ariffin	Senior Principal Analyst (Macro & Future Studies) Malaysian Industry-Government Group for High Technology, Level 6, Block 2, Menara PjH, P.O.Box 11 & 12, Precint 2, 62100 Putrajaya, Malaysia
Tutorial Chair		ISQED/ASQED
Plenary Chair	Fong Swee Kiang (SK Fong)	Intel Microelectronics (M) Sdn. Bhd., Penang Design Center (PG2), Bayan Lepas Free Industrial Zone, Phase 3, Halaman Kampung Jawa, 11900 Penang
Publication Chair	Paul Wesling	IEEE/MIMs
Technical Program Chair	Prof. Anatoli Vakhguet	Head School of Engineering Swinburne University of Technology (Sarawak Campus), Tingkat 1, Kompleks Negeri, Jalan Simpang Tiga, 93576 Kuching, Sarawak
Finance Chair	Baharom Kassim	HR Director STATSChipPAC (M) Sdn. Bhd., No. 73, Lorong Enggang, Ulu Klang FTZ, 54200 Kuala Lumpur

Local Organizing Committee

Committee Chair	_Masliza Osman - masliza@shrdc.org.my_
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Logistics/General Info	_Woo May May - maymay@shrdc.org.my_

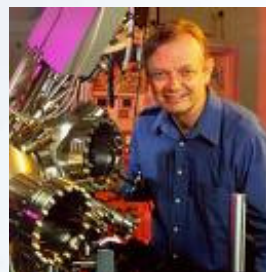
Proposed Speakers





Dr. Chi Foon Chan
President & COO
Synopsys

Dr. Chi-Foon Chan shares responsibility for running the company with Synopsys chairman and CEO Dr. Aart de Geus. Dr. Chan is focused on driving the company's internal operations and worldwide field organization. He joined Synopsys in 1990 as vice president of Applications and Services. Previously at NEC Corporation, Dr. Chan was general manager of the microprocessor group, responsible for marketing all NEC chip devices in North America. Prior to NEC, Dr. Chan was an engineering manager at Intel Corporation. He holds an M.S. and a Ph.D. in Computer Engineering from Case Western Reserve University.



Dr. Stan Williams
Senior Fellow, Director, Quantum Science Research
Hewlett Packard

R. Stanley Williams is an HP Senior Fellow at Hewlett-Packard Laboratories and founding Director of the HP Quantum Science Research (QSR) group, with more than 50 scientists and engineers working in areas of fundamental physical sciences. Established in 1994, QSR is focused on preparing HP for the challenges and opportunities ahead in electronic, photonic and mechanical device technology as features continue to shrink to the nanometer-size scale, where quantum mechanics becomes important. Williams is one of just five active Senior Fellows of a total technical staff of more than 40,000 at HP.

Prof. Kamran Eshraghian

Edith Cowan University, Australia



Kamran Eshraghian is the Foundation Professor of Computer Communication and Electronic Engineering at Edith Cowan University in Western Australia, and Adjunct Professor of Electrical and Electronic Engineering at the University of Adelaide, South Australia. He obtained his Ph.D., M.Eng.Sc., and B. Tech. degrees from the University of Adelaide, South Australia. He is a distinguished world expert in the field of VLSI systems and circuits. His achievements include pioneering research in CMOS VLSI technology encapsulated in the standard text Principles of CMOS VLSI' Design: A Systems Perspective, used in over 500 universities throughout the world. He has held over 40 patents, co-authored six textbooks - two of which have been translated into Japanese, Chinese, Korean and Greek. He is also the editor of the Silicon Systems Engineering series published by Prentice Hall

Shekhar Y. Borkar

*Intel Fellow, Corporate Technology Group
Director, Microprocessor Technology Lab*
INTEL CORPORATION



Shekhar Y. Borkar is an Intel Fellow, Corporate Technology Group and Director of Microprocessor Technology Lab. Borkar is responsible for directing research in technologies for Intel's future microprocessors.

Borkar joined Intel in 1981. He worked on the design of the 8051 family of microcontrollers, iWarp multicomputer and high-speed signaling technology for Intel supercomputers. Borkar is an adjunct member of the faculty of the Oregon Graduate Institute. He has published over 60 articles and holds 41 patents.

Borkar was born in Mumbai, India. He received a master's degree in Electrical Engineering from the University of Notre Dame in 1981, and a master and bachelor degrees in Physics from the University of Bombay in 1979.

Dr. Meyya Meyyappan

Director of the Center for Nanotechnology
NASA Ames Research Center



Meyya Meyyappan, Ph.D., Director of the Center for Nanotechnology as well as Senior Scientist at NASA Ames Research Center in Moffett Field, CA. He is a founding member of the Interagency Working Group on Nanotechnology (IWGN) established by the Office of Science and Technology Policy (OSTP). The IWGN is responsible for putting together the National Nanotechnology Initiative. Dr. Meyyappan is a Fellow of the Institute of Electrical and Electronics Engineers (IEEE). He is Fellow of the Electrochemical Society (ECS). In addition, he is a member of American Society of Mechanical Engineers (ASME), Materials Research Society (MRS), American Vacuum Society (AVS) and American Institute of Chemical Engineers (AIChE). He is the IEEE Distinguished Lecturer on Nanotechnology and ASME's Distinguished Lecturer on Nanotechnology. He is currently the President-elect of the IEEE Nanotechnology Council.

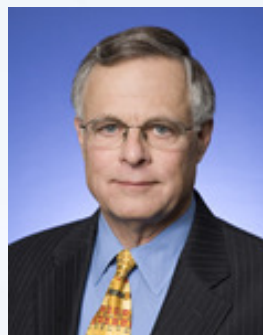
Joseph Fjelstad

Founder and President
Verdant Electronics



Verdant Electronics founder and President Joseph (Joe) Fjelstad has more than 35 years of international experience in electronic interconnection and packaging technology in a variety of capacities from chemist to process engineer and from international consultant to CEO. Mr. Fjelstad is also a well known author and magazine columnist writing on the subject of electronic interconnection technologies. Prior to founding Verdant, Mr. Fjelstad co-founded SiliconPipe a leader in the development of high speed interconnection technologies. He was also formerly with Tessera Technologies, a global leader in chip-scale packaging, where he was appointed to the first corporate fellowship for his innovations.

Dr. Richard Swanson
Founder, CEO and President
SunPower



Dr. Richard Swanson co-founded SunPower in 1985. He has served as president and chief technical officer since June 2003 and has been a member of the board of directors since 1985. Prior to his current position, Dr. Swanson served as chief executive officer and president from 1991 to June 2003 and vice president and director of technology from 1990 to 1991. From 1976 to 1991, Dr. Swanson served as a professor of electrical engineering at Stanford University. He holds a Ph.D. from Stanford University and both bachelor's and master's degrees in electrical engineering from Ohio State University.
<http://www.synopsys.com/Company/PressRoom/PublishingImages/Print/ChiFoonChan.jpg>

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- Nikos Konofaos University of Aegean, Greece
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Sponsorship



Sponsorship

- 4 Categories
 - Titanium – USD10k cash sponsorship
 - Platinum – USD5k cash sponsorship
 - Gold 1 – MYR10k seat allocation
 - Gold 2 – MYR5k seat allocation

	Titanium USD10k	Platinum USD5k	Gold 1 MYR10k	Gold 2 MYR5k
<i>Target Number of Companies</i>	3	3	5	5
Company Logo on all Media / Promotion Items Such as flyers, brochures, website * Company Name stated for Gold category	√	√	√	√
Booth	√	√		
Seats Allocation	4 Seats	2 Seats	5 Seats	2 Seats
Luncheon / Dinner Host	√	√		
Acknowledgement during Symposium	√	√		
Company Short Presentation during Symposium	√	√		
Logo Printed on Participants' Kit	√	√		
Post Event Follow Up (provision of participants contacts)	√	√		

Thank You

